

is capable of withstanding high temperatures of at least one of an IC die bonding operation and normal IC operation.

55.(Once Amended) An electronic system as claimed in claim 52, the stiffener being planar and mounted to a die-side major planar surface of the substrate.

56.(Once Amended) An electronic system as claimed in claim 52, the stiffener having an internal window therein to provide clearance for at least one of a die, under-fill, die side components (DSC), and integrated heat spreader (IHS).

57.(Once Amended) An electronic system as claimed in claim 52, the stiffener being a multi-part stiffener.

58.(Once Amended) An electronic system as claimed in claim 52, the stiffener having an above-substrate-plane height, which is less-than or equal to an above-substrate-plane height, when mounted, of one of: an IC-die, and a combination of an IC-die with an integrated heat spreader (IHS).

59.(Once Amended) An electronic system as claimed in claim 52, the stiffener having a top surface above a substrate-plane, which is substantially co-planar with, when mounted, a top surface of one of: an IC-die, and a combination of an IC-die with an integrated heat spreader.

60.(Once Amended) An electronic system as claimed in claim 59, the stiffener being disposable to co-support a heat sink, with one of: an IC-die, and a combination of an IC-die with an integrated heat spreader (IHS).

61.(Once Amended) An electronic system as claimed in claim 52, where if a main body of the stiffener is electrically conductive, the stiffener further includes an insulator to electrically insulate electrical members on stiffener-opposing areas of the substrate.

62.(Once Amended) An electronic system as claimed in claim 52, the stiffener being an edge stiffener mounted to minor-planar side-surfaces of the substrate.

63.(Once Amended) An electronic system as claimed in claim 52, the edge stiffener having a non-flat cross section which is mated with the side-surfaces of the substrate.

64.(Once Amended) An electronic system as claimed in claim 52, where the edge stiffener is pre-attached to the substrate by an IC-PCB carrier package manufacturer.

REMARKS

This Amendment is responsive to the Office Action identified above, and is responsive in any other manner indicated below.